



FORM PTO-1595 (Rev. 6-93) OMB No. 0651-0011 (exp. 4/94)	101127591	EET	U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
To the Honorable Commissioner of Pater		ached original documents or	copy thereof.
1. Name of conveying part(ies):	2. Name and	address of receiving pa	rty(ies)
Chih-Jen Huang and Shih-Fang Hong	Name:	United Microelectro	nics Corp.
Additional name(s) of conveying party(ies) attached? □Yes ⊠No	Street Address	s: No. 3, Li-Hsin Rd. I Park, Hsinchu City,	
	Name:	United Semiconductor	Corp.
	Street Address:	No. 3, Li-Hsin Rd. II. Park, Hsin-Chu City,	Corp.  , Science-Based Industrial Taiwan, R.O.C.  attached?  Yes No
	Addit	tional name(s) & address(es)	attached? □ Yes ☒ No
3. Nature of conveyance:			. <del>Σ</del>
<ul><li>☑ Assignment</li><li>☐ Merger</li><li>☐ Security Agreement</li><li>☐ Change of Name</li><li>☐ Other:</li></ul>			
Execution Date: August 11, 1999			
4. Application number(s) or patent number(s):			
If this document is being filed together with a new a	pplication, the execution date of	the application is: Au	gust 11, 1999
	B. Patent No.(s)	09/375	_
A. Patent application No.(s)	Additional numbers attached?  Yes	<b>1</b>	
Name and address of party to whom correspondence concerning document should be mailed:	e 6. Total numb	er of applications/pate	nts involved: [1]
Daniel R. McClure Thomas, Kayden, Horstemeyer & Risley, L.L.P. 100 Galleria Parkway, Suite 1500 Atlanta, Georgia 30339			
	7. Total fee ( ☐ Enclose ☐ Authoriz		
	20-0778	ccount Number:	g by Deposit Account)
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true copy of the original document.			<b>-</b> -
Type Name of Person Signing - Daniel R. McClure	Date	lg. 17, 17	7/
	ages including cover sheet, attachments,	and document: [3]	

## **ASSIGNMENT**

WHEREAS.

1. Chih-Jen Huang

Shih-Fang Hong

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: FABRICATION METHOD FOR GATE STRUCTURE HAVING GATE DIELECTRIC LAYERS OF DIFFERENT THICKNESSES

ſ	] Filed:	Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, 1. United Microelectronics Corp., of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

2. United Semiconductor Corp., of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

## **ASSIGNMENT CONTINUED**

Signature:

Sole or First Joint Inventor: Chih-Jen Huang

Shih - Fang Hong

Signature:

Date:

Date:

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s)

Second Joint Inventor (if any): Shih-Fang Hong

indicated.